Features

- Low $R_{DS(on)}$
- Ultra-low Q_G For High Efficiency
- Logic Level
- Light Weight
- Compact Hermetic Package
- Source Sense Pin
- Total Ionizing Dose LDR Immune
- Total Ionizing Dose HDR Immune

Applications

- Satellite and Avionics
- Deep Space Probes
- High Speed Rad-Hard DC-DC Conversion
- Rad-Hard Motor Controllers

EPC7007BC

Rad-Hard eGaN® 200 V, 24 A,
29 mΩ Surface Mount (FSMD-B)

Description

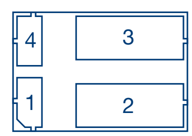
EPC Space FSMD-B series of eGaN® power switching HEMTs have been specifically designed for critical applications in the high reliability or commercial satellite space environments. These devices have exceptionally high electron mobility and a low temperature coefficient resulting in very low $R_{DS(on)}$ values. The lateral structure of the die provides for very low gate charge (Q_G) and extremely fast switching times. These features enable faster power supply switching frequencies resulting in higher power densities, higher efficiencies and more compact packaging.

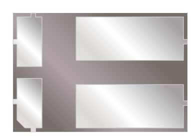
Thermal Characteristics

Symbol	Parameter-Conditions	Value	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (Note 3)	56	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	4.02	

I/O Pin Assignment *(Bottom View)*

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source
4	SS	Source Sense





Absolute Maximum Rating *(T_C = 25°C unless otherwise noted)*

Symbol	Parameter-Conditions	Value	Units
V_{DS}	Drain to Source Voltage (Note 1)	200	V
I_D	Continuous Drain Current ID @ V_{GS} = 5 V, T_C = 25°C	24	A
I_{DM}	Single-Pulse Drain Current $t_{pulse} \leq$ 80 µs	96	
V_{GS}	Gate to Source Voltage (Note 2)	+6 / -4	V
T_J , T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C
T_{sol}	Package Mounting Surface Temperature	260	
ESD	ESD Class	1A (ΔA)	
Weight	Device Weight	0.135	g

Electrical Characteristics *(T_C = 25°C unless otherwise noted. Typical (TYP) values are for reference only.)*

Parameter	Symbol	Test Conditions		MIN	TYP	MAX	Units
Maximum Drain to Source Voltage	V_{DSMAX}	V_G = 0 V		200			V
Drain to Source Leakage	I_{DSS}	V_{DS} = 200 V, V_{GS} = 0 V	T_C = 25°C		10	150	µA
			T_C = 125°C			300	
Gate to Source Forward Leakage	I_{GSSF}	V_{GS} = 6 V	T_C = 25°C		5	600	
Gate to Source Reverse Leakage	I_{GSSR}	V_{GS} = -4 V	T_C = 25°C		100	200	
Gate to Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, I_D = 8 mA	T_C = 25°C	0.8	1.2	2.5	V
Gate to Source Threshold Voltage Temperature Coefficient	$\Delta V_{GS(th)}/\Delta T$	$V_{DS} = V_{GS}$, I_D = 8 mA	-55°C < T_A < 150°C		|3.2|		mV/°C
Drain to Source Resistance (Note 4)	$R_{DS(on)}$	I_D = 24 A, V_{GS} = 5 V	T_C = 25°C		21	29	mΩ
Source to Drain Forward Voltage	V_{SD}	I_S = 0.5 A	T_C = 25°C		2	3	V

Dynamic Characteristics *(T_C = 25°C unless otherwise noted. Typical (TYP) values are for reference only.)*

Parameter	Symbol	Test Conditions	MIN	TYP	MAX	Units
Input Capacitance	C_{ISS}	f = 1 MHz, V_{DS} = 100 V, V_{GS} =0 V		525	1400	pF
Output Capacitance	C_{OSS}			256	360	
Reverse transfer Capacitance	C_{RSS}			1.5	10	
Gate Resistance (Note 5)	R_G	f = 1 MHz, $V_{DS} = V_{GS}$ = 0 V				Ω
Total Gate Charge (Note 6)	Q_G	I_D = 24 A, V_{GS} = 5 V, V_{DS} = 100 V		5.4	7	nC
Gate to Drain Charge (Note 6)	Q_{GD}			1	5	
Gate to Source Charge (Note 6)	Q_{GS}			1.7	3	
Output Charge (Note 5)	Q_{OSS}	V_{GS} = 0 V, V_{DS} = 100 V		37		
Source to Drain Recovery Charge (Note 5)	Q_{RR}	I_D = 24 A, V_{DS} = 100 V		<1		

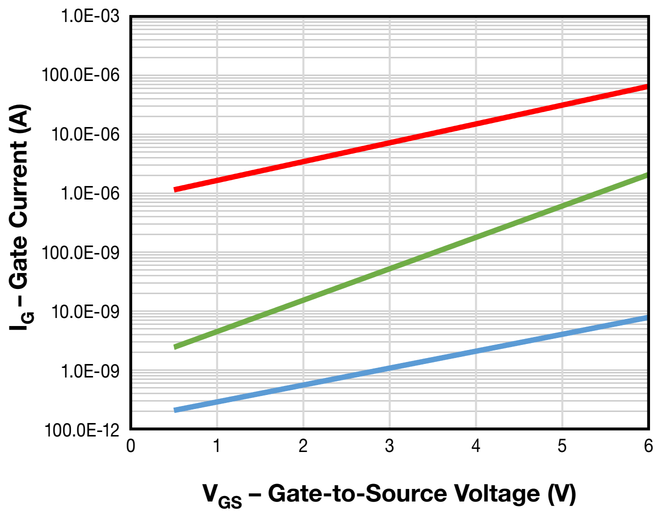


Figure 1. Gate-to-Source Leakage Current vs. Ambient Temperature

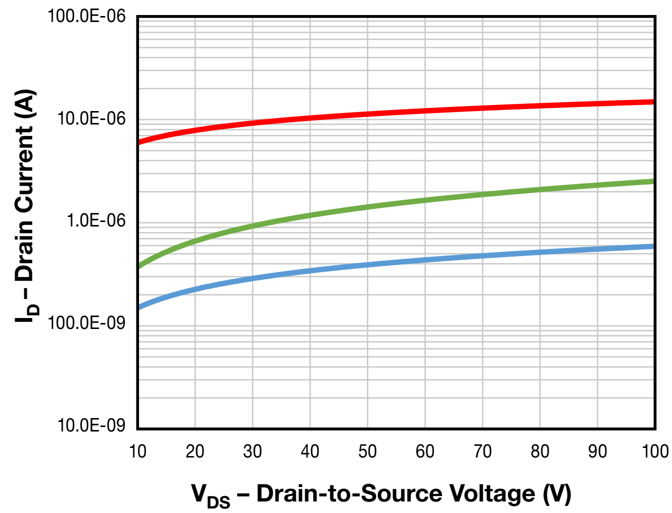


Figure 2. Typical Drain-to-Source Leakage Current vs. Ambient Temperature

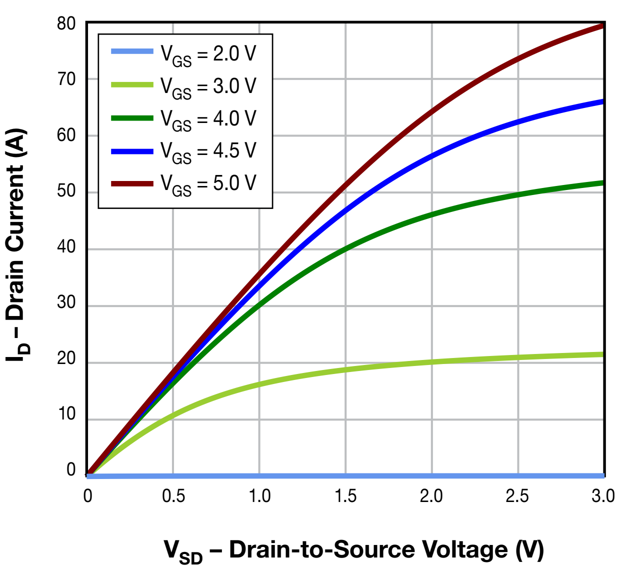


Figure 3. Normalized Threshold Voltage vs.Temperature

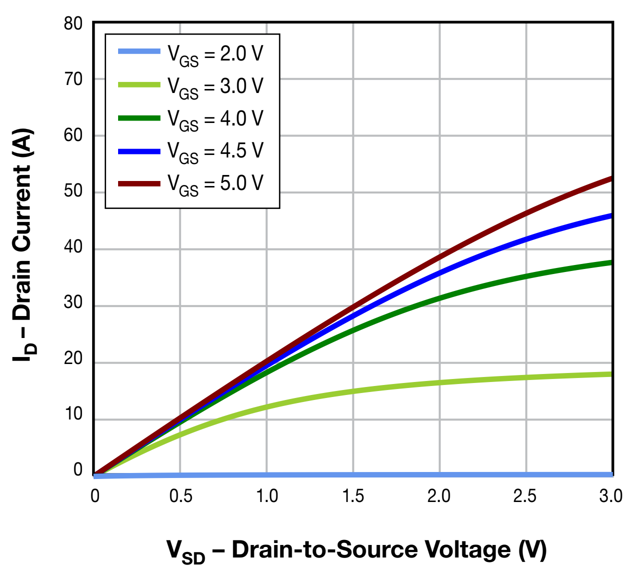


Figure 4. Typical Output Characteristics

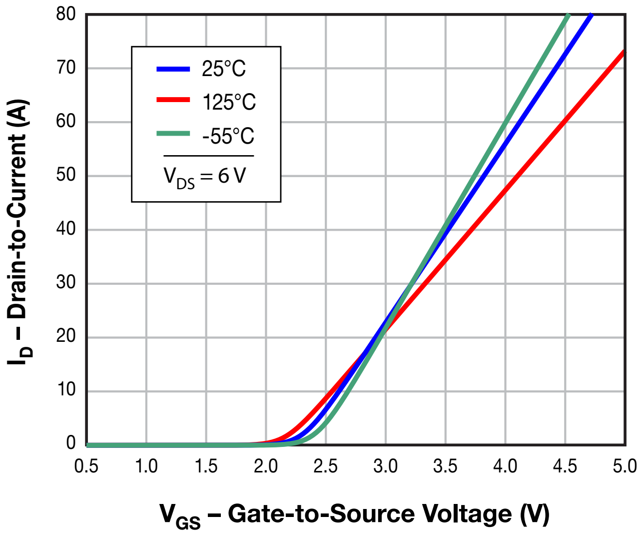


Figure 5. Typical Transfer Characteristics

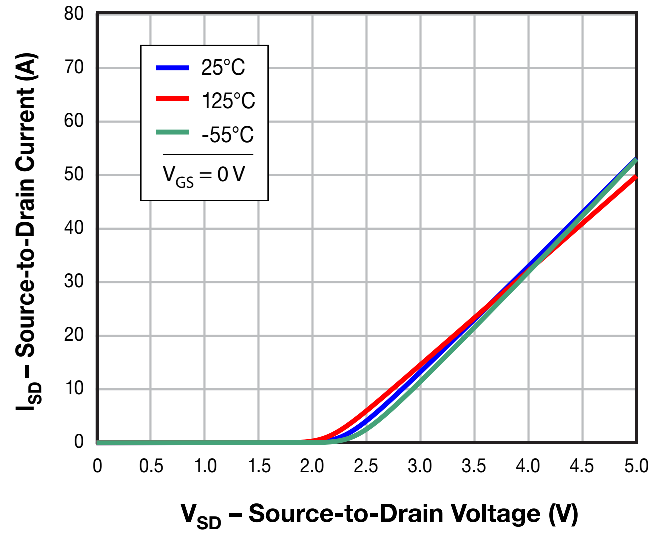


Figure 6. Typical Reverse Drain to Source Characteristics

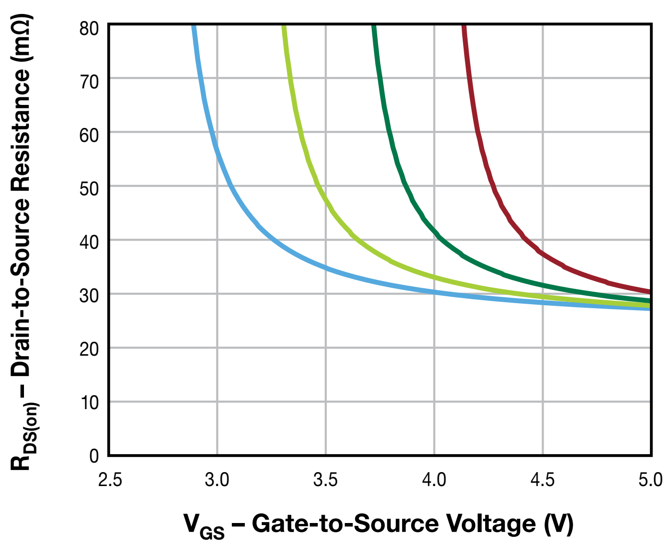


Figure 7. Typical Drain-Source ON Resistance vs. Gate-Source Voltage vs. Ambient Temperature

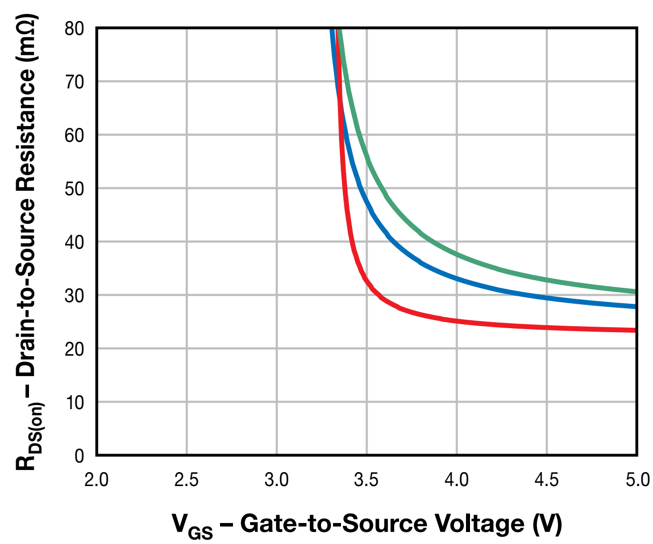


Figure 8. Typical Drain-Source ON Resistance vs. Gate-Source Voltage vs. Drain Current

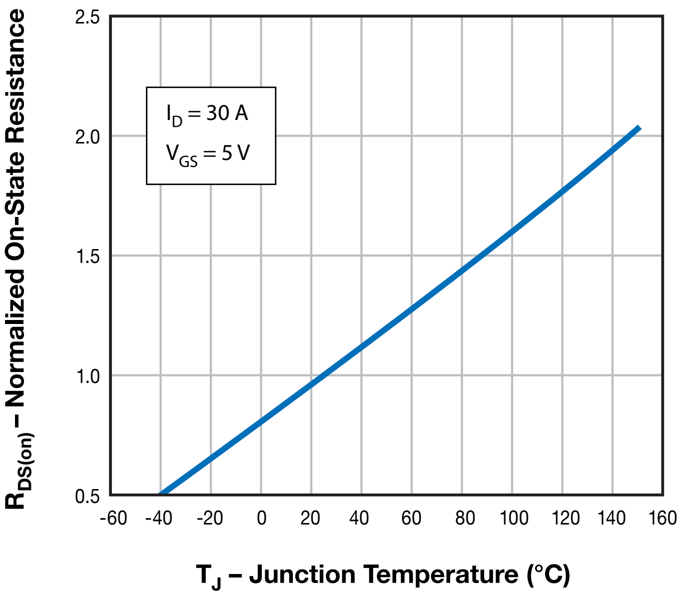


Figure 9. Normalized On-State Resistance vs. Temperature

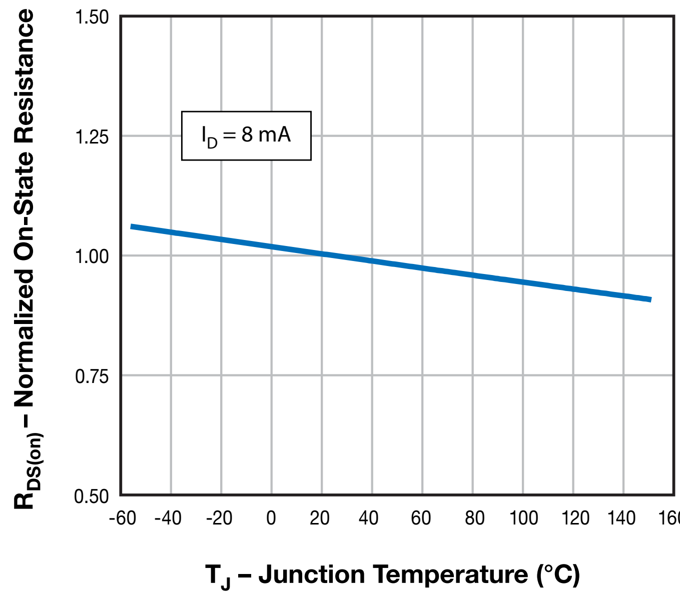


Figure 10. Normalized Threshold Voltage vs. Temperature

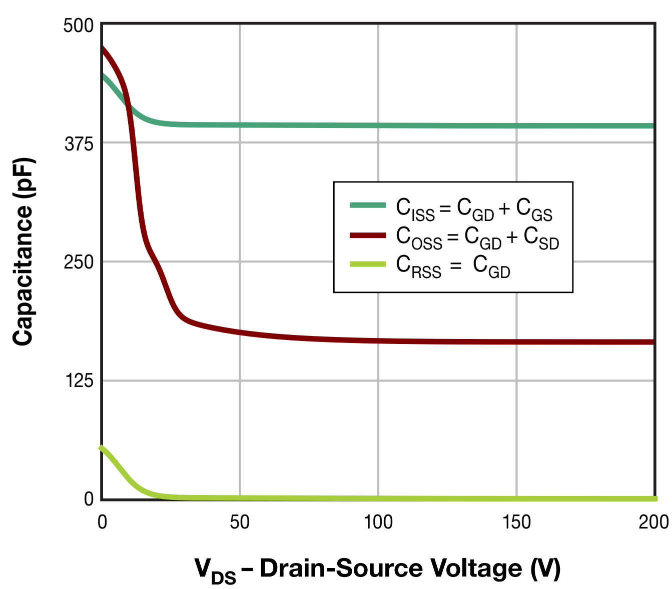


Figure 11. Typical Capacitance

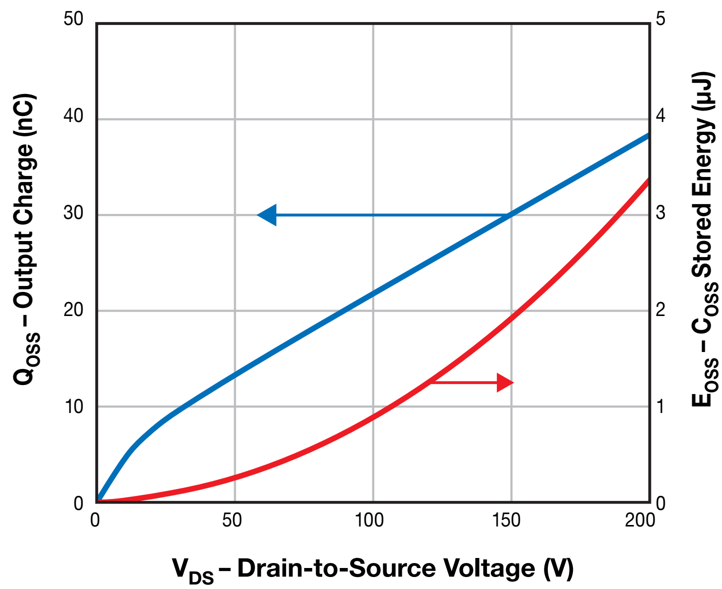


Figure 12. Typical Output Charge and C_{OSS} Stored Energy

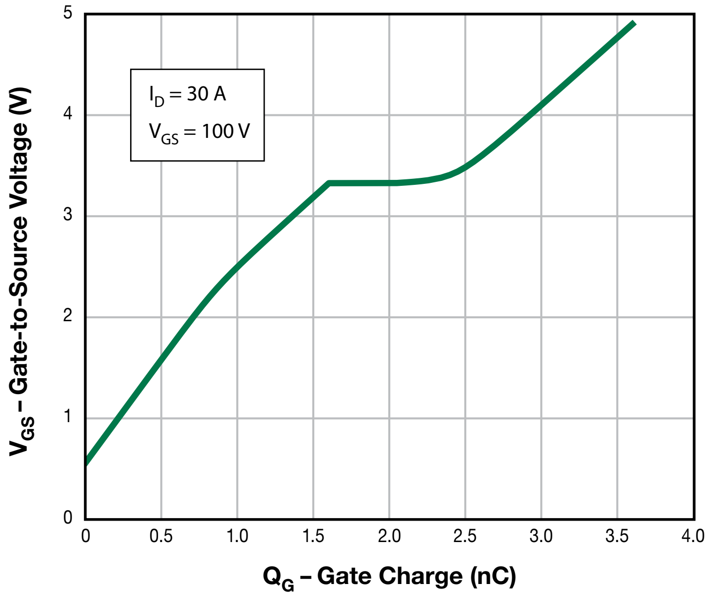


Figure 13. Safe Operating Area

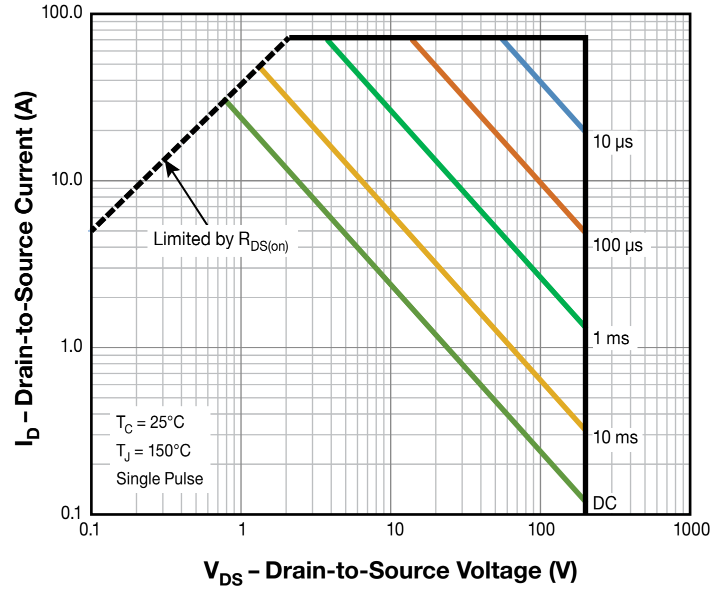


Figure 14. Safe Operating Area

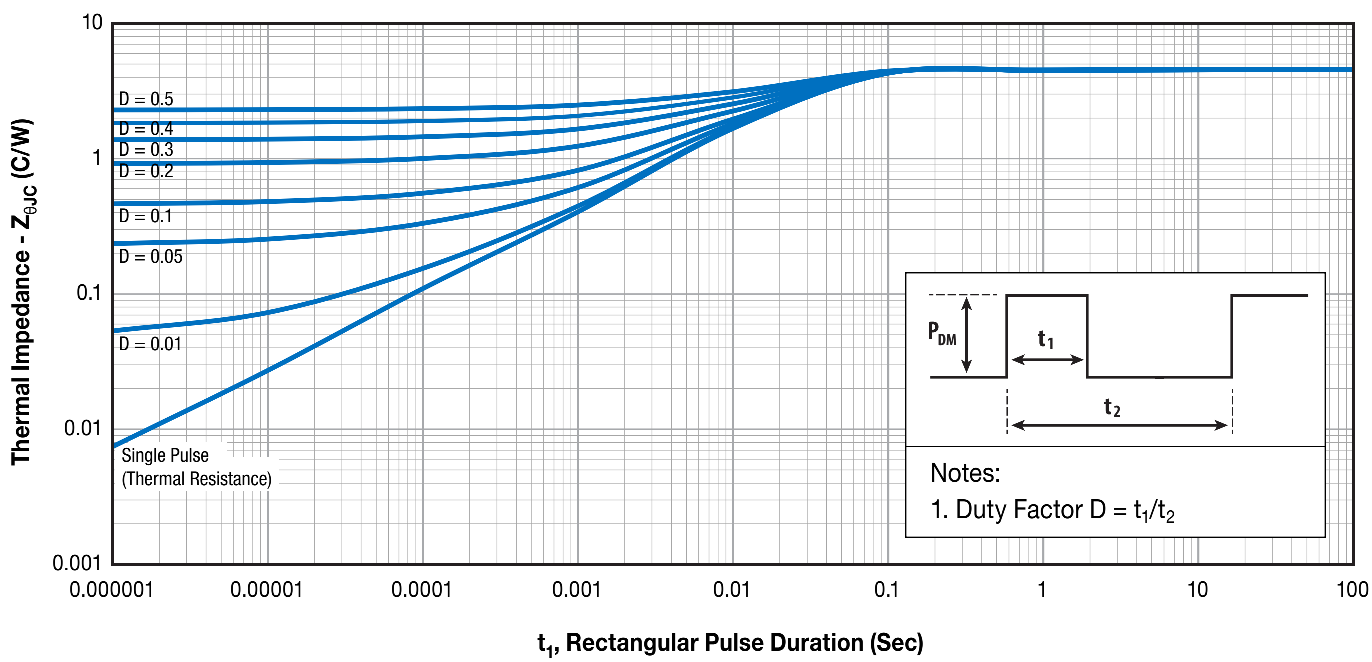
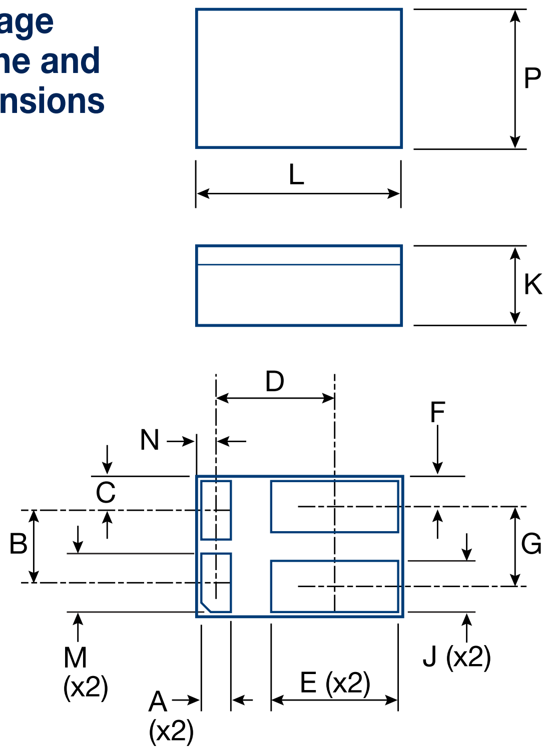


Figure 15. Transient Thermal Impedance, Junction to Case

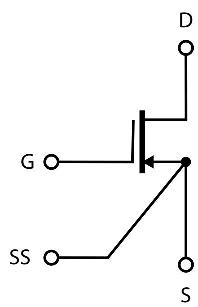
Package Outline and Dimensions



Symbol	IN		MM	
	NOM	REF	NOM	REF
A	0.32		0.81	
B	0.078		1.98	
C		0.036		0.91
D	0.127		3.23	
E	0.137		3.48	
F		0.032		0.81
G	0.087		2.21	
J	0.05		1.27	
K		0.083		2.11
L	0.22		5.69	
M	0.063		1.6	
N		0.021		0.53
P	0.15		0.38	

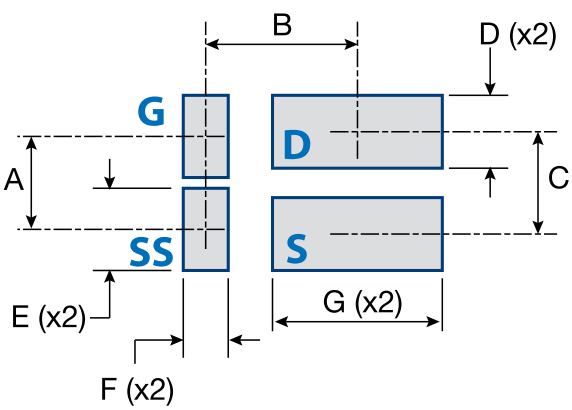
Note: All dimensions have a tolerance of ±0.005 in [±0.13 mm]
Standard Terminal Pad finish is a solder alloy of 63%Sn 37%Pb

Package Connections



NOTE: SS pin is connected directly to source of internal die.

FSMD-B Footprint for Printed Circuit Board Design



Symbol	IN	MM	Note
	NOM	NOM	
A	0.078	1.93	
B	0.127	3.23	
C	0.087	2.21	
D	0.061	1.55	
E	0.069	1.75	
F	0.038	0.97	
G	0.142	3.61	

Suggested footprint:
NOM. DIM = .003 in [0.08 mm] swell on average

Notes

Note 1. Never exceed the absolute maximum V_{DS} of the device otherwise permanent damage/destruction may result.

Note 2. Never exceed the absolute maximum V_{GS} of the device otherwise permanent damage/destruction may result. We recommend a V_{GS} of 5 V for optimum operation across life and radiation.

Note 3. $R_{\theta JA}$ measured with FSMD-B package mounted to double-sided PCB, 0.063” thickness with 1.0 square inches of copper area on the top (mounting side) and a flood etch (3 square inches) on the bottom side.

Note 4. Measured using four wire (Kelvin) sensing and pulse measurement techniques. Measurement pulse width is 80 µs and duty cycle is 1%, maximum.

Note 5. Guaranteed by design/device construction. Not tested.

Note 6. Guaranteed by design/device construction. Not tested. The gate charge parameters are measured based on the MIL-STD-750.3471 Condition B. A high speed constant gate current (I_{const}) is provided to the Gate of the DUT during the time that the ground switch (G_S) is OFF (t_{off}).. The DUT is switched ON and OFF using ground-sensed switch G_S. The gate current is adjusted to yield the desired charge per unit time ((I_{const} · time per division) on the measuring oscilloscope. The G_S pulse drive ON time (t_{on}) is adjusted for the desired observability of the gate-source voltage (V_{GS}) waveform. The maximum duty cycle of the ground switch t_{off}/t_{on}) should be set to 1% maximum. Please note that all gate-related signals are referenced to the “Source Sense” pin on the package. At all times during the measurement, the maximum gate-source voltage is clamped to 5 V_{Dc}

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